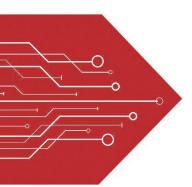
# MSKSEMI















**ESD** 

TVS

**TSS** 

MOV

**GDT** 

**PLED** 

Broduct data sheet



Semiconductor



#### **FEATURES**

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
   For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- Low power loss,high efficiency
   Built-in strain relief,ideal for automated placement
- → High forward surge current capability
   → High temperature soldering guaranteed: 250°C/10 seconds at terminals



#### **MECHANICAL DATA**

**Case**: JEDEC DO-214AC molded plastic body **Terminals**: leads solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight: 0.003 ounce, 0.093 grams 0.004 ounce, 0.111 grams SMA(H)



**SMA** 

#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

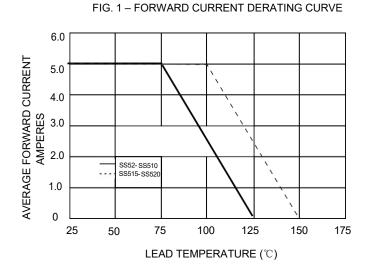
CHARACTERISTICS	SYMBOL	SS52	SS53	SS54	SS55	SS56	SS58	SS510	SS515	SS520	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	20	30	40	50	60	80	100	150	200	V
Maximum RMS Voltage	VRMS	14	21	28	35	42	56	70	105	140	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	20	30	40	50	60	80	100	150	200	V
Maximum Average Forward Rectified Current 0.375" (9.5mm) Lead Lengths	l(AV)	5.0					А				
Peak Forward Surage Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load(JEDEC Method)	IFSM	100					А				
Maximum Forward Voltage at 5.0A DC	VF		0.55		0	.7	0.	.85	0	.95	V
Maximum DC Reverse Current @TJ=25℃ at Rated DC Bolcking Voltage @TJ=100℃	lr		0.2 20					1.0 50	•		mA
Typical Junction Capacitance (Note1)	Сл	500		350					pF		
Typical Thermal Resistance (Note2)	R <b>e</b> ja	15			10					°C/W	
Operating Temperature Range	TJ			-55 to +150					$^{\circ}$		
Storage Temperature Range	Tstg	6		-55 to +150					$^{\circ}$		

NOTES: 1.Measured at 1.0 MHz and applied reverse voltage of 4.0V DC

2. Thermal resistance junction to ambient,







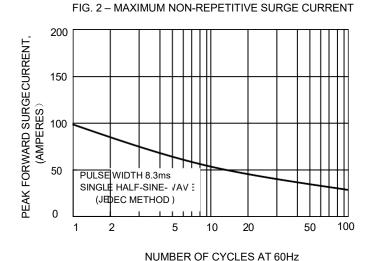


FIG.3 - TYPICAL JUNCTION CAPACITANCE

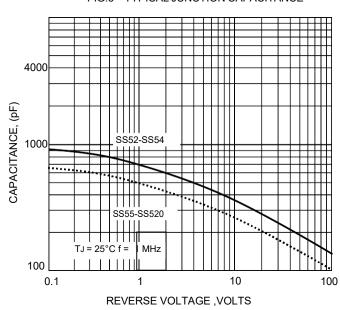
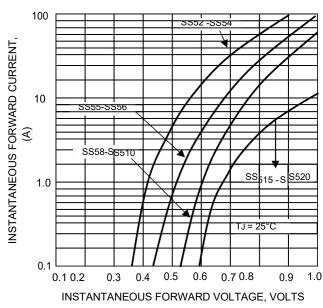
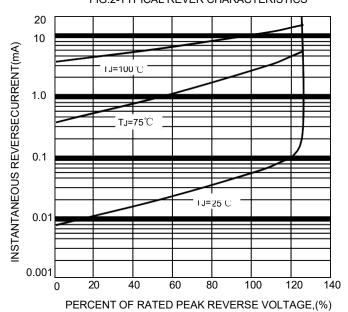


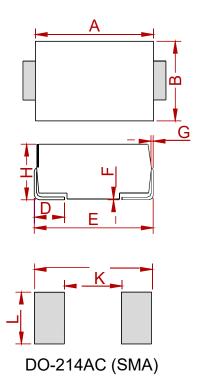
FIG.4-TYPICAL FORWARD CHARACTERISTICS



### FIG.2-TYPICAL REVER CHARACTERISTICS



# **PACKAGE MECHANICAL DATA**



	Dimensions							
Ref.	Millin	neters	Inches					
	Min.	Max.	Min.	Max.				
Α	4.25	4.65	0.167	0.183				
В	2.50	2.90	0.098	0.114				
С	1.35	1.65	0.053	0.065				
D	0.76	1.52	0.030	0.060				
Е	4.93	5.28	0.194	0.208				
F	0.051	0.203	0.002	0.008				
G	0.15	0.31	0.006	0.012				
Н	1.98	2.41	0.078	0.095				
J	6.50		0.256					
K		2.30		0.090				
L	1.70		0.067					

# **REEL SPECIFICATION**

P/N	PKG	QTY
SS52 THRU SS520	SMA	2000

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Compiance

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